# eFPGAs for Advanced Detector Readout

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## Motivation from HEP

- Detectors at future energy frontier colliders (EIC, FCC, muC) will need to accommodate a variety of unique challenges: ○ High granularity → *high data rate*
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	- Spatial constraints → *low material budget, low power consumption*
	- High radiation dose → *custom front-end electronics design*
- Transmission of data off the detector is often less efficient than data processing  $\rightarrow$  push data processing close to the front-end
- **Custom AI/ML-based front-end can provide intelligent filtering or featurization of data at-source,** to handle highly granular detectors, high pileup, and/or increased signal efficiency



# Why eFPGAs for HEP-ML?

- Embedded FPGA (eFPGA) technology can offer reconfigurable logic within an ASIC
	- Low latency to the data after digitization
	- Ease of FPGA configurability on an ASIC: *crucial for dynamic data-taking application*
- Several popular FPGA architectures are over 20+ years old
	- **○ Original patents have expired**
	- **○** Includes Spartan-3 and Virtex-II FPGAs from AMD/Xilinx
- **● → Open source framework "FABulous" available for eFPGA design** 
	- Lowers barrier to entry for chip design



#### eFPGA in the Front End: Simplified Concept Drawing



#### Current eFPGA Prototypes Efforts

- SLAC tapped out two eFPGAs designed with **FABulous** framework
	- 130nm & 28nm:
		- 8 x 8 tiles
		- Small logical capacity (~500 LUTs)
	- [28nm ideal node for harsh radiation](https://indico.cern.ch/event/1255624/contributions/5443894/attachments/2727720/4742151/Single%20Event%20Effects%20characterization%20of%20a%20commercial%2028%20nm%20CMOS%20technology.pdf) [environments](https://indico.cern.ch/event/1255624/contributions/5443894/attachments/2727720/4742151/Single%20Event%20Effects%20characterization%20of%20a%20commercial%2028%20nm%20CMOS%20technology.pdf)



130nm **CMOS** (SLAC)



- LBNL **also** taped out an eFPGA designed with **FABulous** framework
	- 180nm CMOS: 10x16 tiles

# Physics Test Case #1: Smart Pixel Readout

- eFPGAs for at-source inference in low-level pixel sensor data
	- Using Fermilab "smart pixel" dataset
	- Train ML model to classify high-pT from pileup tracks at source, and compress to run in eFPGA
- **● In Feb. 2024 achieved first proof-of-concept configuration of toy eFPGA with track classifier Boosted Decision Tree (BDT) with 100% accuracy to quantized software result!** 
	- Only ~few % background rejection: need to scale up to realistic logical capacity
- *● JINST paper in preparation with 130nm/28nm designs and proof-of-concept ML*







# Physics Test Case #2: Classification in Scintillator Emission

- ASICs integrated with required analog blocks (front-ends, ADCs, TDCs, etc) and eFPGA for real-time, AI/ML aided triggering decisions
- **Feasibility study conducted for** n/g discrimination with sparse BDT/fcNN models
	- Currently working on demonstrator of full signal chain w/ model deployment on eFPGA test chip
	- *○ JINST paper in preparation*





BDT results from feasibility study; right figure assumes number of boosting rounds = 50

<mark>[J. Johnson](https://indico.slac.stanford.edu/event/8288/contributions/7651/)</mark> (LBNL) <sup>7</sup>

Two possible signal chains; top used for feasibility study

## Vision for Work Package

- Increased intelligence in data processing is a key priority of the DOE Basic Research Needs (BRN) [[1](https://science.osti.gov/-/media/hep/pdf/Reports/2020/DOE_Basic_Research_Needs_Study_on_High_Energy_Physics.pdf)] and US budget exercise for future Higgs factory[[2306.13567](https://arxiv.org/abs/2306.13567)]
- **Wide scope for potential university participation**: lower the barrier to entry for ASIC design and engage/train US microelectronics workforce<br>○ Conversations with university partners
	- ongoing (Hawaii, UPenn)
- Considerable synergy with MAPS, precision timing, 4D tracking and calorimetry, and other AI/ML in microelectronics
- $\rightarrow$  *Envision potential to merge with other AI/ML-electronics topics (RDC5, others) for CPAD proposal towards university detector R&D FOA*



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#### 6.3.1: Al/ML in ASICs

- Title: Build out AI/ML functionality in IP blocks, such as data compression, realtime classification or feature extraction, intelligent power management, or front-end programmability.
- Duration: 10 years
- Priority: High
- · Justification: Leverage novel, powerful, and diverse ML-based data handling methods to address the challenges of large complex future collider data-taking, including high input dimensionality (data compression), fast evaluation timescales, and challenging inference tasks (classification, regression, feature extraction).
- Milestones:
	- Conceptual design for generic AI/ML in ASICs including simple classification, regression, and compression algorithms in both the digital and/or analog space  $(FY28)$
	- Prototypes for generic AI/ML ASICs respecting expected experimental restrictions on latency, power consumption, granularity, etc. (FY31)
	- Experiment-specific prototypes for AI/ML-based readout ASICs, coherent with trigger and DAQ developments as described in Section 7 (FY33)

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Help | Adv

#### Work Package Objectives

- 1. Organize a set of **physics targets** for eFPGA use and provide community access to development datasets.
- 2. Build out the **FABulous open source framework with common IP blocks:**
	- a. Optimization for extreme environments such as high radiation or cryogenic temperature
	- b. Optimized for higher logic cell density compared to digital auto placement/routing
- 3. Make available a library of **eFPGA IP blocks**, to enable broad adoption of eFPGA technology and design capability across US labs/universities.
- 4. Incorporate future collider detector specifications, understand context for eFPGAs in future detector design, and promote **eFPGAs as a viable readout option for detector concepts in the 5-10 year timescale**.

#### What's next?

- Next steps: co-design of higher-performance 28nm eFPGA for variety of pixel readout tasks (SLAC)
- Happy for more collaborators!



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